#12/IOS DIGUZ G AGHF129223

DOCKET NO. CHITTIPEDDI 59-108

**PATENT** 

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of:

Sailesh Chittipeddi, et al.

Serial No.:

09/467,253

Filed:

December 20, 1999

For:

WIRE BONDING METHOD FOR COPPER INTERCONNECTS

IN SEMICONDUCTOR DEVICES

Group No.:

2823

Examiner:

Estrada, Michelle

Commissioner for Patents Washington, D. C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks,

(Signature of the person signing the co

Sir:

## <u>INFORMATION DISCLOSURE STATEMENT</u>

In accordance with 37 C.F.R. §1.56 and the provisions of 37 C.F.R. §§1.97 and 1.98 and §609 of the Manual of Patent Examining Procedure, Applicant hereby makes a disclosure of the patents, publications and other information listed below and on the accompanying form PTO-1449, which may be potentially material to the patentability of the invention disclosed in the above-referenced application. Pursuant to § 1.97(e) the Applicant hereby states that each item of information contained in the information disclosure statement was cited in a communication from

a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

U.S. Patent No.	Inventor	<u>Date</u>
5,785,236	Cheung et al.	July 28, 1998
5,172,212	Baba	December 15, 1992
Foreign Patent No.	Country	<u>Date</u>
EP 1 022 776 A2	EP	26 July 2000
EP 0 523 547 A2	EP	20 January 1993
EP 0 178 170	EP	16 April 1986

Applicant hereby certifies that each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement.

As attorney for the Applicant, I am signing below on the basis of the information supplied by an individual designated in § 1.56(c).

Respectfully submitted,

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